LNJ624C4CRA

Hight Bright Surface Mounting Chip LED

3528 (PLCC2) Type

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	80	mW	
Forward current	I_{F}	20	mA	
Pulse forward current *	I_{FP}	70	mA	
Reverse voltage	V _R	V _R 5		
Operating ambient temperature	T _{opr}	-40 to +100	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color

Ambient temperature T_a (°C)

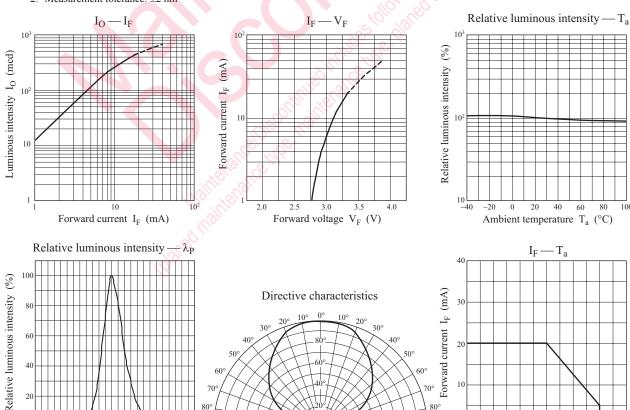
• Pure Green

■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	I _O	$I_F = 10 \text{ mA}$	140	290	380	mcd
Reverse current	I _R	$V_R = 5 V$		W Cho	100	μА
Forward voltage	V _F	$I_F = 10 \text{ mA}$	111	3.2	3.9	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$	YIJC,	520		nm
Dominant emission wavelength *2	$\lambda_{ m d}$	$I_F = 10 \text{ mA}$	523	530	540	nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$	dille	30		nm

Note) *1: Measurement tolerance: ±15%

Peak emission wavelength λ_P (nm)

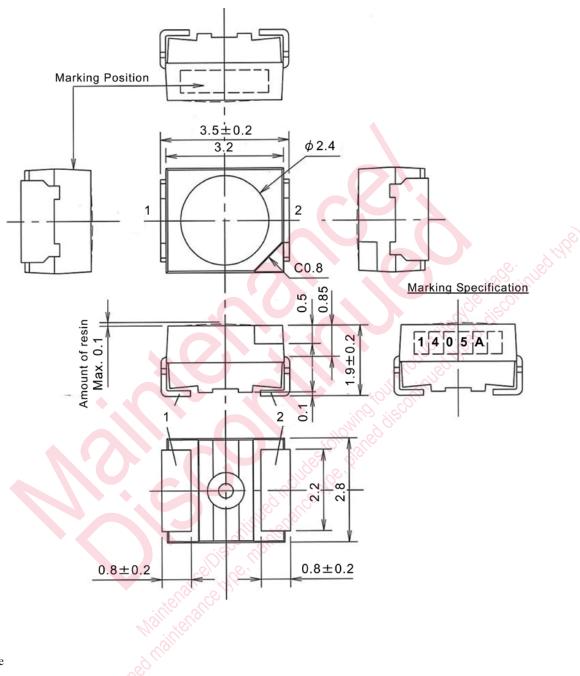


Relative luminous intensity (%)

^{*2:} Measurement tolerance: ±2 nm

■ Package (Unit: mm)

LLDFTR4J2400



- Pin name
 - 1: Anode
 - 2: Cathode

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